Preferred Device

Triacs

Silicon Bidirectional Thyristors

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

Features

- Blocking Voltage to 800 Volts
- On-State Current Rating of 8.0 Amperes RMS at 100°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dv/dt 250 V/µs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating di/dt 6.5 A/ms minimum at 125°C
- Pb-Free Packages are Available*

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

| Characteristic | Symbol | Value | Unit |
|---|---------------------------------------|-------------------|------------------|
| Peak Repetitive Off- State Voltage [,] (Note 1) ($T_J = -40$ to 125°C, Sine Wave, 50 to 60 Hz, Gate Open) | V _{DRM,} V _{RRM} | | V |
| MAC8D MAC8M MAC8N | | 400 600 800 | |
| On-State RMS Current, (Full Cycle Sine Wave, 60 Hz, T _C = 100°C) | I _{T(RMS)} | 8.0 | A |
| Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_J = 125^{\circ}C$) | I _{TSM} | 80 | A |
| Circuit Fusing Consideration (t = 8.3 ms) | l ² t | 26 | A ² s |
| Peak Gate Power (Pulse Width \leq 1.0 μ s, T _C = 80°C) | P _{GM} | 16 | W |
| Average Gate Power (t = 8.3 ms, T_C = 80°C) | P _{G(AV)} | 0.35 | W |
| Operating Junction Temperature Range | Τ _J | - 40 to +125 | °C |
| Storage Temperature Range | T _{stg} | - 40 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

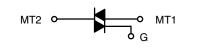
 V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

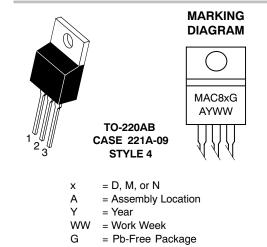


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| PIN ASSIGNMENT | | | |
|----------------|-----------------|--|--|
| 1 | Main Terminal 1 | | |
| 2 | Main Terminal 2 | | |
| 3 | Gate | | |
| 4 | Main Terminal 2 | | |
| | | | |

ORDERING INFORMATION

| Device | Package | Shipping |
|--------|-----------------------|-----------------|
| MAC8D | TO-220AB | 50 Units / Rail |
| MAC8DG | TO-220AB (Pb-Free) | 50 Units / Rail |
| MAC8M | TO-220AB | 50 Units / Rail |
| MAC8MG | TO-220AB (Pb-Free) | 50 Units / Rail |
| MAC8N | TO-220AB | 50 Units / Rail |
| MAC8NG | TO-220AB (Pb-Free) | 50 Units / Rail |

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Preferred devices are recommended choices for future use and best overall value.

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THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|---------------------|-------|------|
| Thermal Resistance, Junction-to-Case | $R_{	ext{	heta}JC}$ | 2.2 | °C/W |
| Thermal Resistance, Junction-to-Ambient | R_{\thetaJA} | 62.5 | °C/W |
| Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds | TL | 260 | °C |

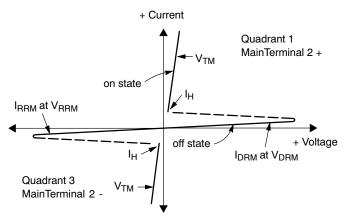
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted; Electricals apply in both directions)

| Characteristic | Symbol | Min | Тур | Max | Unit |
|--|--|-------------------|----------------------|-------------------|------|
| OFF CHARACTERISTICS | | • | • | • | • |
| Peak Repetitive Blocking Current (V _D = Rated V _{DRM} , V _{RRM} ; Gate Open) $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$ | I _{DRM} , C I _{RRM} | - | - | 0.01 2.0 | mA |
| ON CHARACTERISTICS | | | | • | |
| Peak On-State Voltage (Note 2), ($I_{TM} = \pm 11 \text{ A Peak}$) | V _{TM} | - | 1.2 | 1.6 | V |
| Gate Trigger Current (Continuous DC) ($V_D = 12 V$, $R_L = 100 \Omega$) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) | I _{GT} | 5.0 5.0 5.0 | 13 16 18 | 35 35 35 | mA |
| Holding Current, (V _D = 12 V, Gate Open, Initiating Current = \pm 150 mA) | Iн | - | 20 | 40 | mA |
| Latching Current (V _D = 24 V, I _G = 35 mA), MT2(+), G(+); MT2(-), G(-) MT2(+), G(-) | ١L | - | 20 30 | 50 80 | mA |
| Gate Trigger Voltage (V_D = 12 V, R_L = 100 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-) | V _{GT} | 0.5 0.5 0.5 | 0.69 0.77 0.72 | 1.5 1.5 1.5 | V |
| Gate Non-Trigger Voltage (V _D = 12 V, R _L = 100 Ω, T _J = 125°C) MT2(+), G(+); MT2(+), G(-); MT2(-), G(-) | V _{GD} | 0.2 | - | - | V |
| DYNAMIC CHARACTERISTICS | | | | • | |
| Rate of Change of Commutating Current See Figure 10.($V_D = 400 \text{ V}$, $I_{TM} = 4.4 \text{ A}$, Commutating dv/dt = 18 V/µs,Gate Open, $T_J = 125^{\circ}$ C, f = 250 Hz, No Snubber) $C_L = 10 \ \mu\text{F}$ $L_L = 40 \text{ mH}$ | (di/dt) _c | 6.5 | - | - | A/ms |
| Critical Rate of Rise of Off-State Voltage (V_D = Rated V_{DRM} , Exponential Waveform, Gate Open, T_J = 125°C) | dv/dt | 250 | - | - | V/μs |

2. Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%.

Voltage Current Characteristic of Triacs (Bidirectional Device)

| Symbol | Parameter |
|------------------|---|
| V _{DRM} | Peak Repetitive Forward Off State Voltage |
| I _{DRM} | Peak Forward Blocking Current |
| V _{RRM} | Peak Repetitive Reverse Off State Voltage |
| I _{RRM} | Peak Reverse Blocking Current |
| V _{TM} | Maximum On State Voltage |
| Ι _Η | Holding Current |

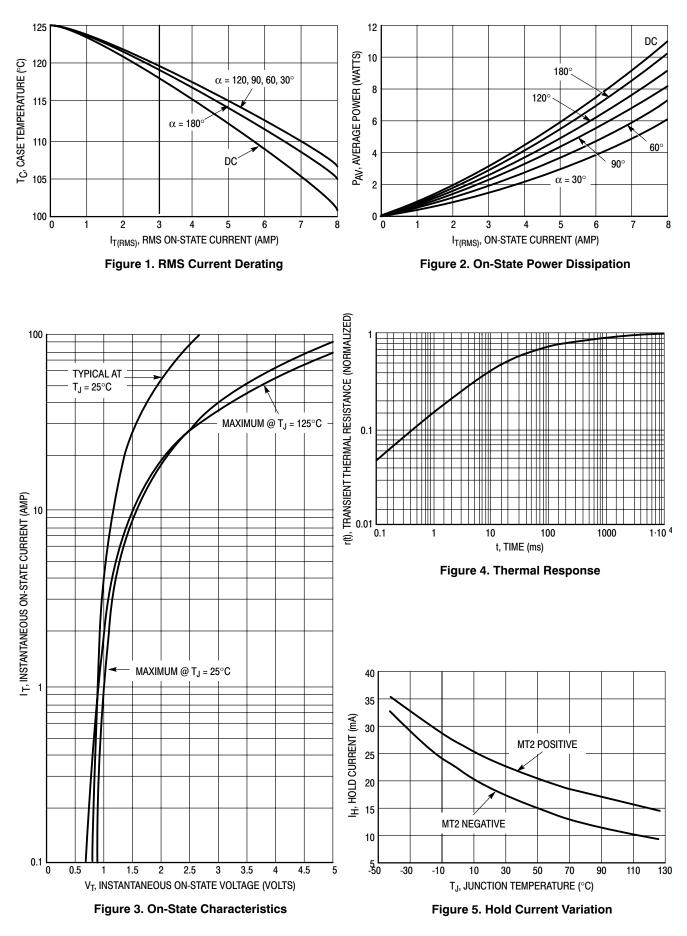


MT2 POSITIVE (Positive Half Cycle) (+) MT2 (+) MT2 Quadrant II (+) I_{GT} Quadrant I (-) I_{GT} 0 o **ф** МТ1 **ф** МТ1 Ξ -REF REF I_{GT} + I_{GT} (-) MT2 (-) MT2 Quadrant III (+) I_{GT} GATE **Quadrant IV** (-) I_{GT} 0 O-MT1 **ф** МТ1 Ξ Ξ REF REF MT2 NEGATIVE (Negative Half Cycle)

Quadrant Definitions for a Triac

All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.



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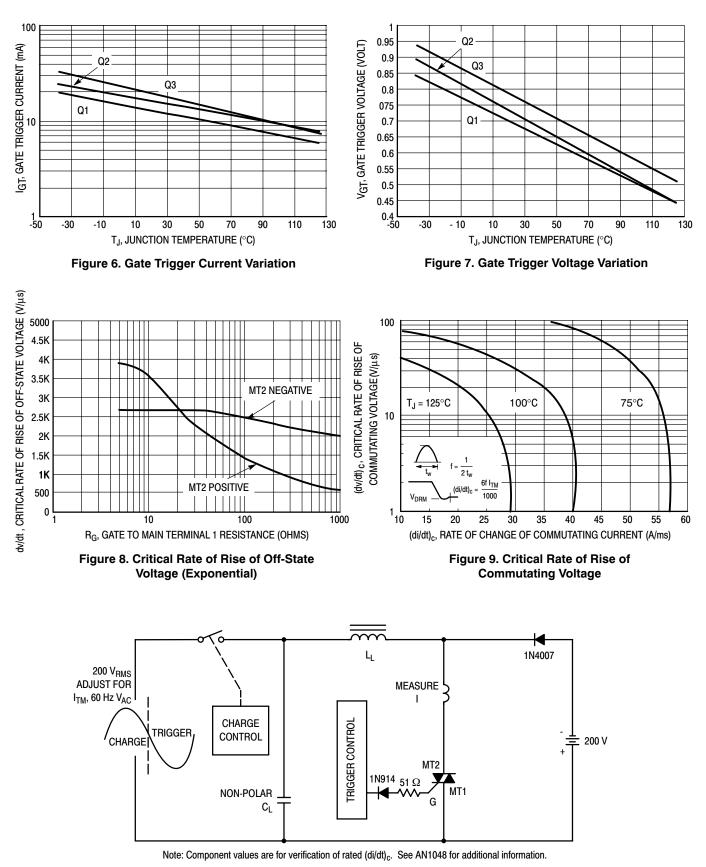
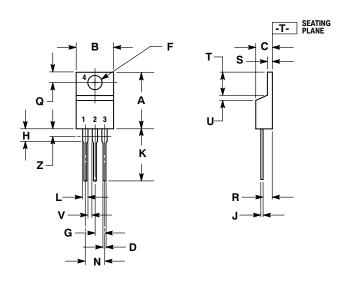


Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AE



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.

2. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED. 3

| | INC | HES | MILLIMETERS | | |
|-----|-------|-------|-------------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.570 | 0.620 | 14.48 | 15.75 | |
| В | 0.380 | 0.405 | 9.66 | 10.28 | |
| С | 0.160 | 0.190 | 4.07 | 4.82 | |
| D | 0.025 | 0.035 | 0.64 | 0.88 | |
| F | 0.142 | 0.161 | 3.61 | 4.09 | |
| G | 0.095 | 0.105 | 2.42 | 2.66 | |
| Н | 0.110 | 0.155 | 2.80 | 3.93 | |
| J | 0.014 | 0.025 | 0.36 | 0.64 | |
| ĸ | 0.500 | 0.562 | 12.70 | 14.27 | |
| L | 0.045 | 0.060 | 1.15 | 1.52 | |
| Ν | 0.190 | 0.210 | 4.83 | 5.33 | |
| Q | 0.100 | 0.120 | 2.54 | 3.04 | |
| R | 0.080 | 0.110 | 2.04 | 2.79 | |
| S | 0.045 | 0.055 | 1.15 | 1.39 | |
| Т | 0.235 | 0.255 | 5.97 | 6.47 | |
| U | 0.000 | 0.050 | 0.00 | 1.27 | |
| V | 0.045 | | 1.15 | | |
| Z | | 0.080 | | 2.04 | |

MAIN TERMINAL 2

2.

3 GATE MAIN TERMINAL 2

4.

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